

BSS192-VB Datasheet

P-Channel 200 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (△)	I _D (A)	Q _g (Typ.)		
- 200	0.8 at V _{GS} = - 10 V	- 1.80	8.0		
	0.9 at $V_{GS} = -6.0 \text{ V}$	- 1.70	0.0		

FEATURES

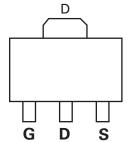
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- Ultra Low On-Resistance
- Small Size

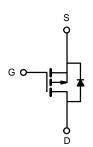




APPLICATIONS

Active Clamp Circuits in DC/DC Power Supplies





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS TA	= 25 °C, unless	otherwise no	oted		
Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	- 200		V
Gate-Source Voltage		V _{GS}	± 20		
Continuous Proin Comment /T 450 90\8 h	T _A = 25 °C	- I _D	- 1.80	- 1.64	
Continuous Drain Current (T _J = 150 °C) ^{a, b}	T _A = 70 °C		- 1.70	- 1.51	
Pulsed Drain Current		I _{DM}	- 5.5		Α
Continuous Source Current (Diode Conduction) ^{a, b}		I _S	- 1.0	- 0.6	
Single Pulse Avalanche Current	L = 1.0 mH	I _{AS}	4.0		
Single Pulse Avalanche Energy	L = 1.0 mn	E _{AS}	1	1.2	
M. D. D. J. J. ah	T _A = 25 °C	P _D	1.45	0.95	W
Maximum Power Dissipation ^{a, b}	T _A = 70 °C		0.8	0.48	V V
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maniana basis a Anking	t ≤ 5 s	R _{thJA}	75	100	°C/W	
Maximum Junction-to-Ambient ^a	Steady State		120	166		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	40	50		

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.



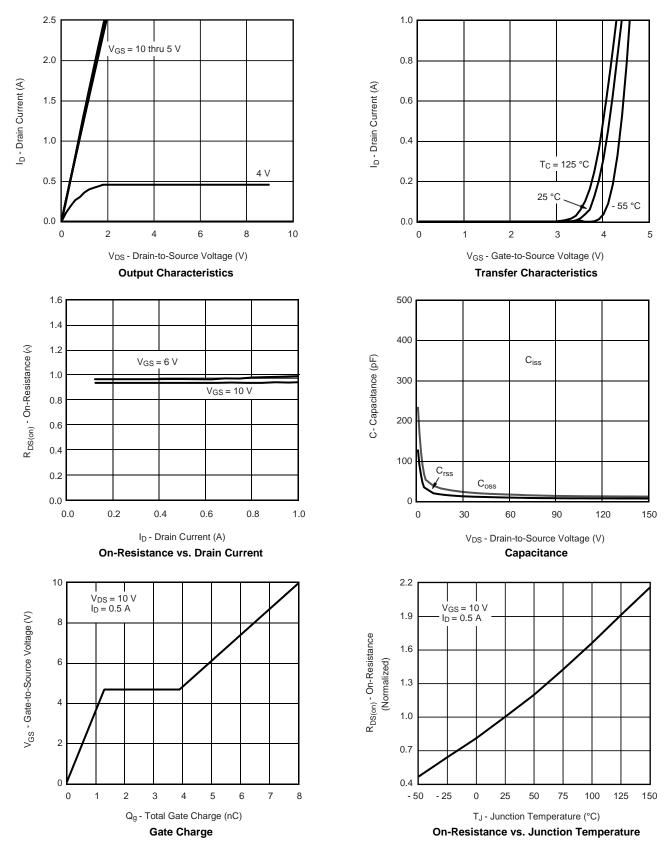
			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур. Мах.		Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 200			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 2.5		- 4.5		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	I _{DSS}	V _{DS} = - 200 V, V _{GS} = 0 V	-1		- 1		
Zero Gate Voltage Drain Current		V _{DS} = - 200 V, V _{GS} = 0 V, T _J = 55 °C			- 10	μΑ	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≤ - 15 V, V _{GS} = 10 V - 1.				Α	
	D	$V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}$		0.80		_ ^	
Drain-Source On-Resistance ^a	R _{DS(on)}	$V_{GS} = -6.0 \text{ V}, I_D = -0.5 \text{ A}$		0.90			
Forward Transconductance ^a 9 _{fs}		$V_{DS} = -15 \text{ V}, I_{D} = -0.5 \text{ A}$		1.8		S	
Diode Forward Voltage	V_{SD}	I _S = - 1.0 A, V _{GS} = 0 V		- 0.85	- 1.2	V	
Dynamic ^b							
Total Gate Charge	Q_g	V 400 V V 40 V		8.0	12	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = -100 \text{ V}, V_{GS} = 10 \text{ V}$ $I_{D} \cong -0.5 \text{ A}$		1.3			
Gate-Drain Charge	Q_{gd}	10= 0.071		2.5			
Gate Resistance	R_g	f = 1.0 MHz		8.0		^	
Input Capacitance	C _{iss}			370	510	pF	
Output Capacitance	C _{oss}	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		28			
Reverse Transfer Capacitance	C _{rss}			16			
Switching ^c							
Turn-On Time	t _{d(on)}	V 400 V D 400		8	12	ne	
rum-on rime	t_r $I_D \cong -1.0 \text{ A}, V_{GEN} = -10 \text{ V}$	$V_{DD} = -100 \text{ V}, R_L = 100 \text{ A}$		11	17		
Turn-Off Time	t _{d(off)}	$R_a = 6 \wedge$		16	25	ns	
Tuin-On Time	t _f	y		11	17		
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F = 0.5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$		140	200	nC	

- a. Pulse test: PW \leq 300 μ s duty cycle \leq 2 %. b. For DESIGN AID ONLY, not subject to production testing. c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

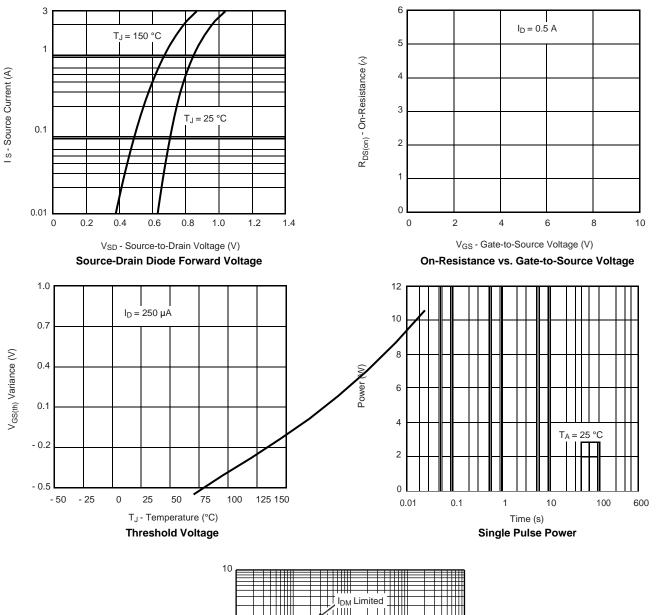


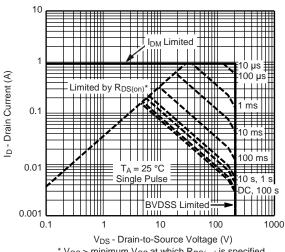
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





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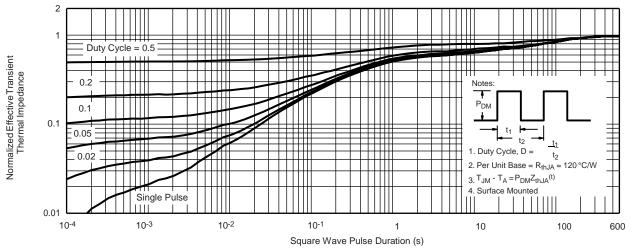


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



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